	COUNT	DESCRIPTION OF REVI		ISIONS BY CHKD DA		DATE		COUNT		DESCRIPTION OF REV		VISIONS	BY	CHK	D D	ATE		
ζ								Δ										
	117047	DIE OTANDAD						Δ										
APPLICABLE STANDARD Operating 55°C to 1105°C (Netto1) Storage 10°C to 150°C (Netto2)																		
RATING		Operating Temperature Range									Temperature Range -10°C to +6				-60°C	60°C (Note3)		
		Operating Humidity Range		20% to 80% (Note2)							ge Hur		40% to 70% (Note3)					
		Applicable Connector								Volta	/oltage 250V AC/DC							
		Applicable Cable		AWG#22						Curre	Current			AWG 22 : 2A				
		Insulation Diameter		ϕ 1.2 $\sim \phi$ 1.45 mm														
SPECIFICATIONS																		
														AT				
CO	<u>NSTR</u>	UCTION																
Gene	ral Exar	nination	Visually	ly and by measuring instrument.						Δ.	According to drawing.						0	
Mark	ing		Confirmed visua					ually.					, tooliding to drawing.					
ELECTRICAL CHARACTERISTICS												•						
Cont	act Res	istance	20mV MAX, 1mA (DC or 1000Hz).								30 mΩ MAX.							
Milliv	olt Leve	l Method														0	-	
			TEDI	OTTO														
MECHANICAL CHARACTERISTICS														I				
Mechanical Operation			30 times insertion and extraction.								①Contact resistance: 30mΩ MAX					0	_	
		(Sn Plating)								2	②No damage, crack or looseness of parts.							
Mech	nanical (Operation	50 times insertion and extraction.							1	①Contact resistance: 30mΩ MAX							
		(Au Plating)								2	②No damage, crack or looseness of parts.							
Vibra	ition		Frequency 10 to 55 Hz, single amplitude 0.75 mm,). ①	(Internal description of the							
			at 10 cycles for 3 direction.							_	①No electrical discontinuity of 1μ s.						-	
0			_								②No damage, crack or looseness of parts.							
Shoc	:K		Acceleration 490 m/s 2 duration of pulse 11 ms at 3 times for 3 directions.							t 3	3						_	
EN\	<u>/IRON</u>	IMENTAL CHA	RAC	TERIS	STICS	<u>S</u>												
Damp	Heat		Exposed at 40 \pm 2 $^{\circ}$ C , humidity 90 to 95 %, 96 h.							n. ①	①Contact resistance: 30 m Ω MAX.							
(Steady State)			(After leaving the room temperature for 1 to 2h.)							2	②No damage, crack or looseness of parts.						_	
Rapid	Change	of	Temperature -55 °C→ +105 °C								①Contact resistance: 30 mΩ MAX.							
Temperature											s. ②No damage, crack or looseness of parts.							
Temperature											- Grade de l'observes de parts.					0	-	
			(The tr	e transferring time of the tank is 2 to 3 MIN) er leaving the room temperature for 1 to 2h.)														
			(After I															
Rema		de the temperature	ricing k	ov curr	ent													
		ondensing	, Hollig L	Jy Curr	CITC.													
Note		y to the condition o	_		_		-		fore p	cb on b	board, a	fter pcb board	, operatir	ng temp	eratu	re and		
	num	dity range is applie	u for int	Leriii Si	Lorage	during t	ransport	ation.										
							DRAWN		DESIGNED		CHECKE	D AF	PROVE	D	RELEA	SED		
							MINA N. II		MINT V II			M 174 S 4 /		EN	<u>c</u>			
						K	KIM. Y. H		KIM. Y. H		LIM. S.	MIL			20. 02			
						1	18.10.02		18	3.10.02	18.10.0	18.10.02 18.10.02		DEPT				
		rise specified, refer to						NDD1 10 15: = =										
NOTE QT: QUALIFICATION TEST AT: ASSURANCE TEST O: APPLICABLE TEST																		
HIROSE KOREA CO.,LTD. SPECIFICATI								ΓΙΟΙ	N SH	SHEET PART NO. DF51K-22SCA (800)))		
CODE NO.(OLD)			l	DRAWING NO.					CODE	E NO.						1 /		
CL				ELC4-611515						CL 6652-0068-2-800								